

Creep Analysis of Lead-Free Solders Undergoing Thermal Loading

Summary

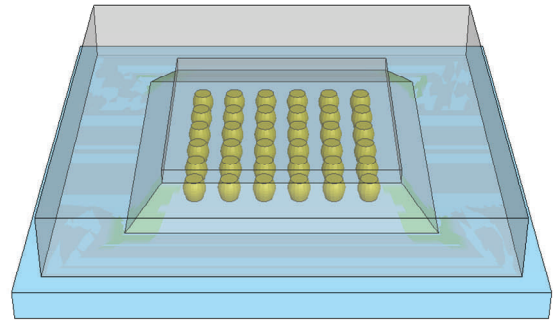
Lead and its compounds have been widely used for many years in the electronics industry. However, the global demand to reduce the use of hazardous materials has compelled electronics manufacturers to consider the use of lead-free materials in future products. This transition has heightened the necessity for new finite element material models that can be used to evaluate the reliability of lead-free solders. Along with extensive nonlinear analysis capabilities, **Abaqus/Standard** includes a variety of creep models - including those applicable to lead-free solders, making it a reliable design tool for the electronics industry.

Background

Lead solders, such as the popular tin-lead variety, have been used in the electronics industry for the past 50 years. Subsequently, their long-term reliability is well understood. However, lead and its compounds are highly toxic and the entry of these materials into the environment has become an issue of great importance. In conjunction with legislation requiring the eventual use of lead-free materials, the electronics industry is working towards reducing the amount of lead in end-user equipment. This transition requires the development of new analytical capabilities for estimating the reliability of components that use lead-free solder.

During their working lives, electronic components are subject to a large number of thermal cycles. Mismatch between the thermal expansion behaviors of the various materials may induce severe stresses that are high enough to cause plasticity and creep. In particular, solder balls are at risk because they are stressed at temperatures above half of the solder's melting point. At such temperatures, the solder creeps; after a number of thermal cycles, the accumulation of large inelastic strains may lead to failure of the solder joints. Therefore, the creep analysis of solder balls under cyclic thermal loading becomes an important part of the design phase.

Abaqus Version 6.6 offers several creep models that are widely used in the electronics industry for lead-free solders. The hyperbolic-sine model is available as a regular feature, and the modified Anand [1] and double-power [2] models are freely available as user subroutines. These models, together with its nonlinear solution techniques and thermal-mechanical coupling capability, make ABAQUS/Standard an ideal tool for analyzing the reliability of electronics components.



Key Abaqus Features and Benefits

- Extensive material library that includes commonly used creep models for lead-free solders
- Sequentially or fully coupled thermal-mechanical analysis capability
- Geometrically nonlinear analysis capability
- Scripting interface to allow customization of ABAQUS/CAE

Finite Element Analysis Approach

Building a BGA model using ABAQUS/CAE

The scripting and GUI toolkit interfaces of ABAQUS allow the capabilities of ABAQUS/CAE to be customized for special applications. With this functionality, many of the specific tasks associated with the development of certain classes of models can be automated. Additionally, a customized application allows non-expert users to run pre-packaged analyses easily.

The Ball-Grid-Array (BGA) model used in this technology brief was built using an ABAQUS/CAE custom application developed at Worley Parsons PTE Limited, Singapore. The user interface is shown in Figure 1.

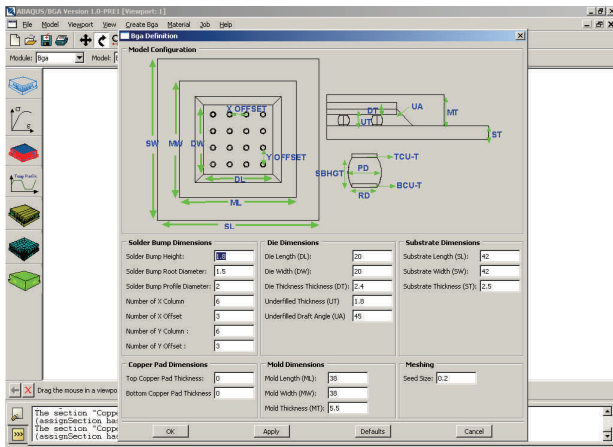


Figure 1: ABAQUS/CAE BGA custom application

The process of building a BGA model is captured in several icons, e.g., the Model icon, the Material icon, the Load icon, etc. For example, only the dimensions for a BGA model need to be specified in the Model dialog box, and the model is built and meshed automatically.

Model description

Figure 2 shows a section of the BGA model used in the present calculations. Thirty-six solder balls connect the silicon die and the substrate, with underfill material used in the space surrounding the solder balls. All components except the substrate are encapsulated in the mold.

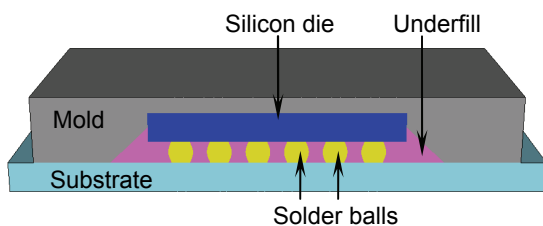


Figure 2: Schematic section view of the BGA model

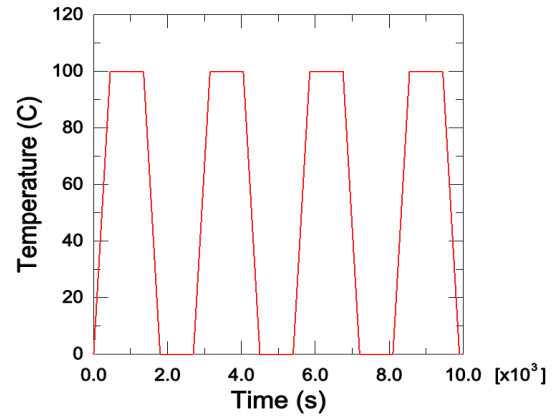


Figure 3: Temperature time history used to apply thermal load

The materials have different thermal expansion coefficients, causing stresses to develop when the model is subject to thermal loading. For simplicity, it is assumed that the entire model is subject to uniform thermal cycling, with the temperature amplitude curve shown in Figure 3. In a more detailed analysis, the temperature field could be obtained from a previous heat-transfer analysis, or the entire simulation could be carried out as a fully-coupled temperature-displacement analysis. The bottom of the substrate is fixed and no other direct mechanical loading is applied.

Results and Discussion

In Figure 4, the distribution of equivalent creep strain (CEEQ) at the end of the analysis ($t=9900$ s) is shown for the array of solder balls. The top surfaces of the solders interface with the silicon die; thermal expansion mismatch between the solder and the surrounding materials results in high creep strain near the top and bottom surfaces of the solders. In addition, the creep strain in solders at the perimeter of the array is higher than that near the center. The solders with the highest creep strains are those at the four corners, suggesting that these are the critical joints for the simulated device.

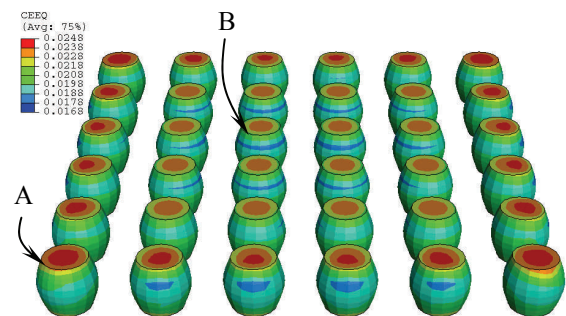


Figure 4: Equivalent creep strain at end of loading history

The time histories of the Mises stress and the equivalent creep strain at locations A and B (see Figure 4) are shown in Figure 5. Note that the modified Anand [1] creep model was used to generate these results. In general, the Mises stress in the corner solder (location A) is slightly higher than that in the solders near the center of the device, especially during the time interval in which the temperature is held constant at 100 °C. The slightly higher stress develops larger creep strains in the corner solders, and the difference in the creep strains steadily increases as the number of thermal cycles increases. Once the creep strain increment per cycle at the critical point of a solder reaches a constant, this value can be used in a fatigue law, such as the Coffin-Manson equation, to estimate the fatigue life of the solder ball.

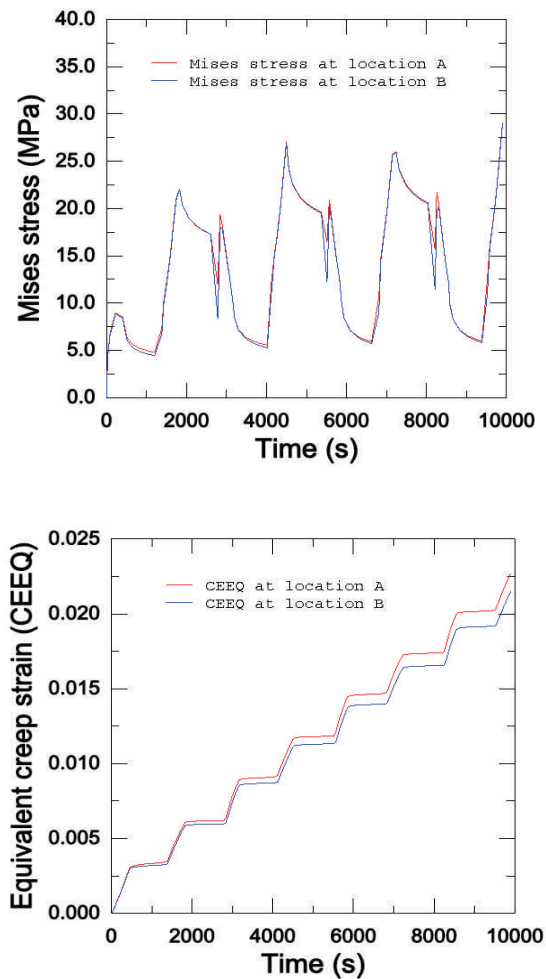


Figure 5: Stress and strain histories at points A and B (Fig 4).

As an additional comparison, Figure 6 shows the creep strains at location A (see Figure 4) obtained from analyses using three creep laws that are often cited in the electronics industry.

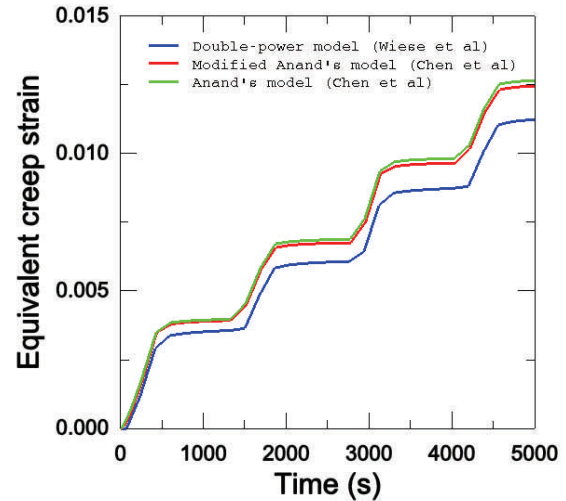


Figure 6: Creep strains obtained using three different creep models

Conclusions

The fast-growing application of lead-free materials in the electronics industry has brought new challenges with regards to the simulation of creep behavior. The advanced features of Abaqus/Standard, including a large material library, extensive nonlinear analysis capability, and thermal-mechanical coupling, have made it a powerful design tool for the electronics industry in the lead-free era.

References

- [1] X. Chen, G. Chen, and M. Sakane, "Prediction of Stress-Strain Relationship with an Improved Anand Constitutive Model for Lead-Free Solder Sn3.5Ag," *IEEE Transactions on Components and Packaging Technologies*, Vol. 28, pp. 111-116, 2005.
- [2] S. Wiese, E. Meusel, K. J. Wolter, "Microstructural Dependence of Constitutive Properties of Eutectic SnAg and SnAgCu Solders," Proceedings of the 53rd ECTC Conference, pp. 197-206, 2003.
- [3] H.S. Ng, T.Y. Tee, S. Pan, et al, "Development and Application of Lead-free Solder Joint Fatigue Model for CSP," Proceedings of the 6th International Conference on Electronics Materials and Packaging, 2004.
- [4] D. Cadge, "ABAQUS for Electronics," Tutorial at the 2006 ABAQUS user conference.

ABAQUS References

For additional information on the Abaqus capabilities referred to in this brief please see the following Abaqus Version 6.6 documentation references:

- Analysis User's Manual
 - Rate-dependent plasticity: creep and swelling, Section 18.2.4
 - Heat transfer and thermal-stress analysis, Section 6.5
 - Solid (continuum) elements, Section 21.1.1
- Abaqus User Subroutines Reference Manual
 - CREEP, Section 1.1.1
- Abaqus Answer 3049, "Creep models for lead-free solder"
- Abaqus Answer 1891, "Modeling the creep of solder"
- Abaqus Scripting Users' Manual

About SIMULIA

SIMULIA is the Dassault Systèmes brand that delivers a scalable portfolio of Realistic Simulation solutions including the Abaqus product suite for Unified Finite Element Analysis, multiphysics solutions for insight into challenging engineering problems, and lifecycle management solutions for managing simulation data, processes, and intellectual property. By building on established technology, respected quality, and superior customer service, SIMULIA makes realistic simulation an integral business practice that improves product performance, reduces physical prototypes, and drives innovation. Headquartered in Providence, RI, USA, with R&D centers in Providence and in Suresnes, France, SIMULIA provides sales, services, and support through a global network of over 30 regional offices and distributors. For more information, visit www.simulia.com

The 3DS logo, SIMULIA, Abaqus, and the Abaqus logo are trademarks or registered trademarks of Dassault Systèmes or its subsidiaries, which include ABAQUS, Inc. Other company, product, and service names may be trademarks or service marks of others.

Copyright © 2007 Dassault Systèmes

